

Free standing film



- self-supporting differential phase changing thermal interface material, contains no substrate (Free Standing Film)
- materials with phase change temperature at 52 °C;
- best thermal conductivity, exceeding phase change temperature point, material flows into all gaps between components and heatsink
- thixotropic, does not migrate from the interface area
- no lowering of thermal conductivity though thermal cycling
- application with very low contact pressure, due to non elastomeric material, particularly suitable for clamp mounting of components
- electrically non-conductive, but not an insulator
- self adhering characteristics, also suitable for large areas
- no toxic ingredients
- custom required shapes on request
- all with protection foil on both sides

art. no.	basin	dimensions [mm]
FSF 52 P	plate, protection foil on both sides	330 x 343 x 0.127 ±0.025

	FSF 52 P
phase change temperature	52 °C
colour	white
tightness	2 g/cm ³
thermal resistance (1 in², TO 3) at contact pressure of	0.03 K/W 0.031 N/mm ²
thermal conductivity	0.9 W/m·K
temperature range	max. +200 °C
adhesive holding force	0.35 N/mm ²
class of flammability	UL 94 V-0
dielectric constant	3.8 [1 kHz] 3.4 [1 MHz]